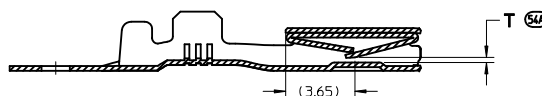
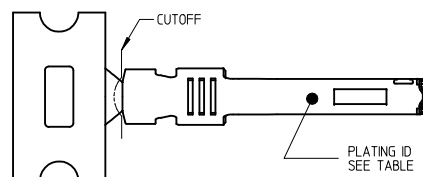
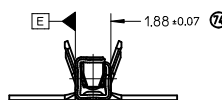
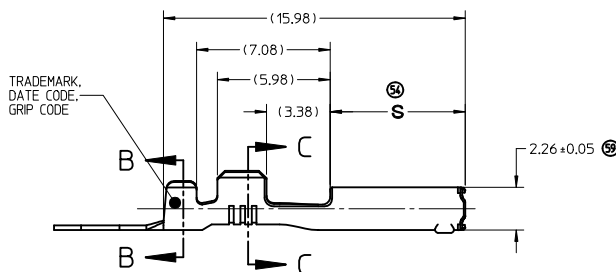
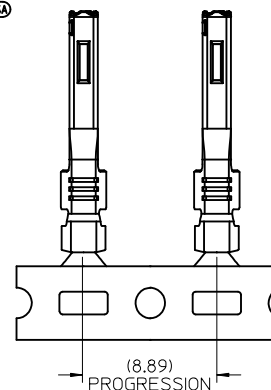


ISO VIEWS
SCALE 3:1



SECTION D-D



NOTES: (UNLESS OTHERWISE SPECIFIED)

1. MATERIALS: SEE TABLE
2. PACKAGING SPECIFICATION: PK-31300-516 AND PK-30907-759
3. CRIMPING PER APPLICATION SPECIFICATION AS-33468-001
4. CRIMPED LEAD MEETS THE FOLLOWING:
 - 4.1 SAE/USCAR-21, MAY 2002
 - 4.2 SAE/USCAR-2, REV. 3, APRIL 2001
 - 4.3 SAE/USCAR-12, REV. 2
 - 4.4 GMW #3191 AUGUST 22, 2000 (DRAFT)
 - TEMPERATURE CLASS 3, APPLIES ONLY TO Au PARTS
 - 4.5 GMW #3191 JANUARY, 2005
 - TEMPERATURE CLASS 3, APPLIES ONLY TO Ag PARTS
5. PLATING NOTES:
 - 5.1 TIN PLATING (ENTIRE TERMINAL)
 - 5.1.1 ELECTRO REFLOW 190 - 330 MICROMETERS TIN OVER 0.25 - 0.76 MICROMETERS NICKEL
 - 5.2 GOLD PLATING
 - 5.2.1 UNDERPLATE OVERALL 125-225 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - 5.2.2 ELECTRODEPOSITED GOLD 0.76 - 15 MICROMETERS IN CONTACT AREAS
 - 5.2.3 ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA
 - 5.3 SILVER PLATING
 - 5.3.1 UNDERPLATE OVERALL 125-225 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - 5.3.2 ELECTRODEPOSITED PURE SILVER 99.5% PURITY SEMI-BRIGHT FINISH WITH NO BRIGHTENERS OR CHROMATES 1.9 - 3.3 MICROMETERS IN CONTACT AREAS
 - 5.3.3 ANTI-TARNISH TREATMENT FOR SILVER PLATED AREA: SYNTHETIC HYDROCARBON CONTACT SURFACE FINISH OR EQUIVALENT
 - 5.3.4 ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA

WIRE SIZE	GRIP CODE	PART NUMBER	REEL PAYOFF DIRECTION	DM A	DM B	DM S	DM T	DM AF	DM AG	BASE MATERIAL	PLATING ID
22 AWG	A	33468-0002	D	2.3	2.3	7.15 ± 0.10	0.26 ± 0.07	(2.9)	(2.1)	COPPER ALLOY	Sn Lead Free
		33468-0001	B	2.3	2.3	6.97 ± 0.10	0.26 ± 0.07	(2.9)	(2.1)	COPPER ALLOY	Au Lead Free
		33467-0004	D	2.3	2.3	6.97 ± 0.10	0.26 ± 0.07	(2.9)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-1001	D	2.3	2.3	6.97 ± 0.10	0.26 ± 0.07	(2.9)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-2001	B	2.3	2.3	6.97 ± 0.10	0.26 ± 0.07	(2.9)	(2.1)	COPPER ALLOY	Ag Lead Free
18/20 AWG	B	33468-0004	D	3.0	2.9	7.15 ± 0.10	0.26 ± 0.07	(2.8)	(2.6)	COPPER ALLOY	Sn Lead Free
		33467-0006	D	3.0	2.9	6.97 ± 0.10	0.26 ± 0.07	(2.8)	(2.6)	COPPER ALLOY	Au Lead Free
		33467-0005	B	3.0	2.9	6.97 ± 0.10	0.26 ± 0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		34736-1002	D	3.0	2.9	6.97 ± 0.10	0.26 ± 0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		34736-2002	B	3.0	2.9	6.97 ± 0.10	0.26 ± 0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free

ENTER DESCRIPTION EC NO: UAU2012-0459 DRAWN BY: DRWINKFERGUSON CHKD: APRR:BMOSER REV: G2	DESCRIPTION 2011/11/01	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
		▽=0	mm INCH
		▽=0	4 PLACES ± --- ± ---
		▽=0	3 PLACES ± --- ± ---
G2	REV	▽=0	2 PLACES ± 0.10 ± ---
		▽=0	1 PLACE ± 0.3 ± ---
		▽=0	ANGULAR ± 3 °
		▽=0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
L. PULLIAM	2/3/2006
CHECKED BY	DATE
D. HEMNANI	2/3/2006
APPROVED BY	DATE
B. MOSER	2/3/2006
MATERIAL NO.	
SEE TABLE	
SIZE	
C	

SCALE 5:1	
DESIGN UNITS METRIC	
THIRD ANGLE PROJECTION	
TITLE MX64 SAE RECEPTACLE TERMINAL	
MOLEX INCORPORATED	
DOCUMENT NO. SD-33468-001	
SHEET NO. 1 OF 1	

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